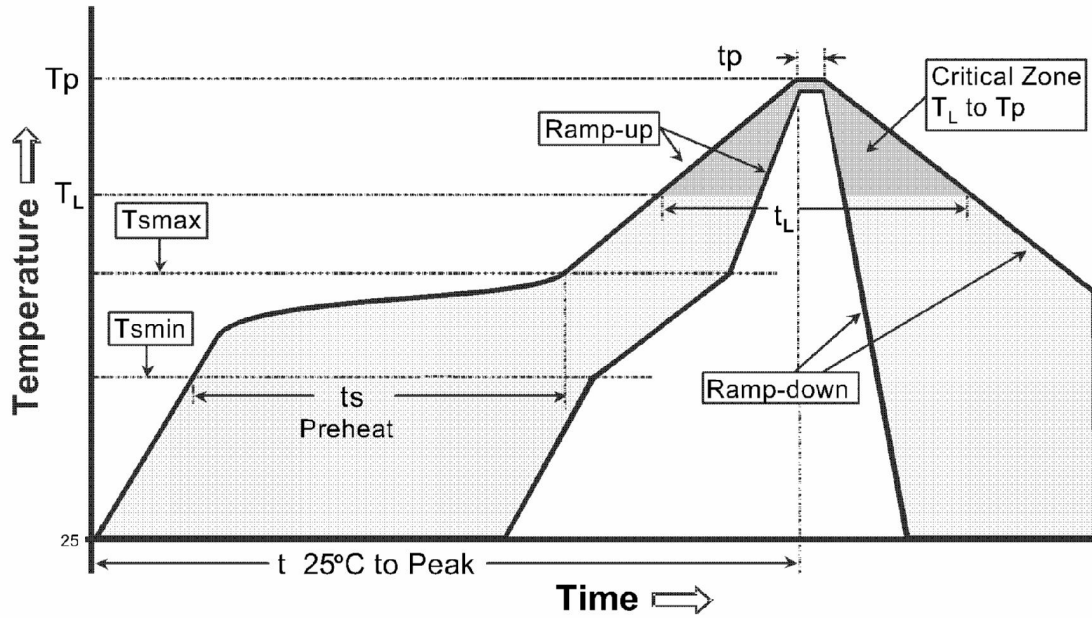


Reflow Soldering Profile 1

260°C +0/-5°C for 10 seconds



Profile Feature	Parameter
Average ramp-up rate	3°C per second
Preheat temperature (minimum): T_{smin}	150°C
Preheat temperature (maximum): T_{smax}	200°C
Preheat time: t_s	60 to 180 seconds
Ramp to peak	3°C per second maximum
Time over liquidus: t_L	60 to 150 seconds
Peak temperature: T_p	260°C
Time within -5°C of peak: t_p	10 seconds maximum
Ramp cool down	6°C per second maximum
Time 25°C to peak: t	8 minutes maximum